



BC847BLP

#### **45V NPN SMALL SIGNAL TRANSISTOR IN DFN1006**

#### Features

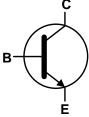
- BV<sub>CEO</sub> > 45V
- I<sub>C</sub> = 100mA High Collector Current
- P<sub>D</sub> = 1000mW Power Dissipation
- 0.60mm<sup>2</sup> Package Footprint, 13 times Smaller than SOT23
- 0.5mm Height Package Minimizing Off-Board Profile
- Complementary PNP Type BC857BLP
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

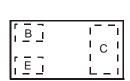
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu.
- Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0009 grams (Approximate)



Bottom View



Device Symbol



Top View Device Schematic

#### Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC847BLP-7	1F	7	8mm	3,000
BC847BLP-7B	1F	7	8mm	10,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

### **Marking Information**

Notes:

BC847BLP-7	● 1F Top View Dot Denotes Collector Side (++++++++++++++++++++++++++++++++++++	From date code 1527 (YYWW), this changes to: Top View Bar Denotes Base and Emitter Side
BC847BLP-7B	Top View Bar Denotes Base and Emitter Side	1F = Product Type Marking Code



# Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current	Ic	100	mA
Peak Pulse Collector Current	I <sub>CM</sub>	200	mA

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	D-	400	mW	
	(Note 6)	P <sub>D</sub>	1,000		
Thermal Desistance, Junction to Ambient	(Note 5)	R <sub>θ</sub> JA	310	0000	
Thermal Resistance, Junction to Ambient	(Note 6)		120	°C/W	
Thermal Resistance, Junction to Lead (Note 7)		$R_{ ext{ heta}JL}$	120	°C/W	
Operating and Storage and Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

# ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

#### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	50			V	I <sub>C</sub> = 100µA, I <sub>B</sub> = 0
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	45		_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6	—	_	V	$I_E = 100 \mu A, I_C = 0$
DC Current Gain	h <sub>FE</sub>	200	350	450	—	$V_{CE} = 5.0V, I_{C} = 2.0mA$
Collector-Emitter Saturation Voltage (Note 9)	V <sub>CE(sat)</sub>	_	80 200	250 600	mV	$I_{C} = 10mA, I_{B} = 0.5mA$ $I_{C} = 100mA, I_{B} = 5.0mA$
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(sat)</sub>	_	700 900	_	mV	$I_{C} = 10mA, I_{B} = 0.5mA$ $I_{C} = 100mA, I_{B} = 5.0mA$
Base-Emitter Voltage (Note 9)	V <sub>BE(ON)</sub>	580 —	640 725	700 770	mV	$V_{CE} = 5.0V, I_C = 2.0mA$ $V_{CE} = 5.0V, I_C = 10mA$
Collector-Cutoff Current	I <sub>CBO</sub>	—	—	15 5.0	nΑ μΑ	V <sub>CB</sub> = 30V V <sub>CB</sub> = 30V, T <sub>A</sub> = +150°C
Gain Bandwidth Product	f⊤	100	_	_	MHz	$V_{CE} = 5.0V, I_C = 10mA, f = 100MHz$
Collector-Base Capacitance	C <sub>CBO</sub>	—	3.0	—	pF	$V_{CB} = 10V, f = 1.0MHz$

Notes: 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air For the device mounted of minimum recommended pad layout roz copper that is on a single-sided 1.5mm PK4 P conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm Zoz copper.
Thermal resistance from junction to solder-point (on the exposed collector pad).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.
Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.



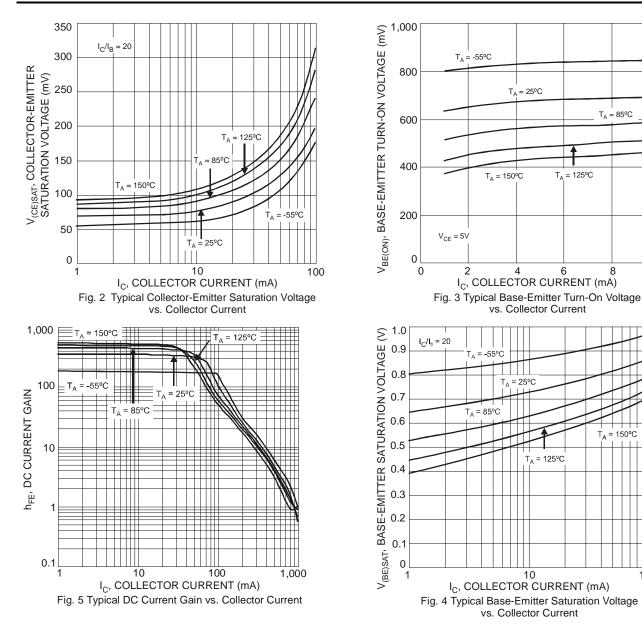
10

= 150°C Τ<sub>Α</sub>

100

 $T_{A} = 85^{\circ}C$ 

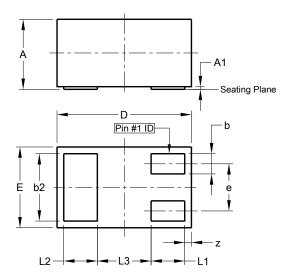
# Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)





# **Package Outline Dimensions**

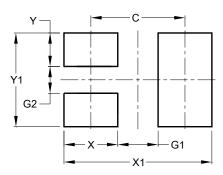
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
ш	0.55	0.675	0.60		
e	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Ŷ	0.25
Y1	0.70



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